

CLEAN VERSION OF AMENDED CLAIMS

1. An electronic device comprising:

a dielectric substrate having a first surface and a second surface, and a via connecting the first and second surfaces, wherein the via has a horizontal cross sectional area;

a first and a second sacrificial copper structure deposited onto the first and the second surface and surrounding the via, respectively, wherein each of the first and second sacrificial copper structures covers an area of no more than three times the horizontal cross sectional area of the via; and

wherein the first and the second sacrificial copper structures are formed on the substrate via a photolithographic process.